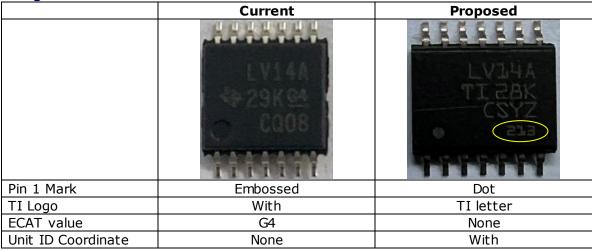
PCN Number:			20230502002.0					PC	N Date:	May 04, 2023
Title: TSSOP Symbo			olization update for select devices							
<b>Customer Contact:</b>			PCN Manager			Dept:	Quality Services			
Change Type:										
	Assembly Site				Assembly Process				Assembly	<sup>,</sup> Materials
	Design				Datasheet				Mechanic	al Specification
☐ Test Site				$\boxtimes$	Packing/Shipping/Labeling				Test Prod	cess
☐ Wafer Bump Site					Wafer Bump Material				Wafer Bu	mp Process
	☐ Wafer Fab Site				Wafer Fab Materials				Wafer Fa	b Process
					Part number change			•		
PCN Details										

## **Description of Change:**

This letter is to inform customers of a device symbolization change for select devices in the TSSOP packages that will enable enhanced device level traceability.

**TSSOP Package Device** 



### **Reason for Change:**

Improved Device traceability

### Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

### **Changes to product identification resulting from this PCN:**

None

# **Product Affected:**

DRV8889AQPWPRQ1	DRV8908QPWPRQ1	TLC5948APWP	TPS92518HVQPWPTQ1
DRV8889QPWPRQ1	DRV8910QPWPRQ1	TLC5948APWPR	TPS92663AQPWPRQ1
DRV8899QPWPRQ1	DRV8912QPWPRQ1	TLC5949PWP	TPS929120AQPWPRQ1
DRV8904QPWPRQ1	LM5122ZAPWPR	TLC5949PWPR	TPS929120QPWPRQ1
DRV8906QPWPRQ1	LM5122ZAPWPT	TPS65270PWPR	TPS929121AQPWPRQ1
DRV8908DQPWPRQ1	SN1111015PWPR	TPS92518HVQPWPRQ1	TPS929121QPWPRQ1

ZVEI ID reference: SEM-PA-13

For questions regarding this notice, e-mails can be sent to the contact below or your local Field Sales Representative.

Location	E-Mail				
WW Change Management Team	PCN www admin_team@list.ti.com				

#### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (<a href="www.ti.com/legal/termsofsale.html">www.ti.com/legal/termsofsale.html</a>) or other applicable terms available either on <a href="ti.com">ti.com</a> or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.